



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2019-04-12
Company Unique ID	NL 008751171801		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement		
Supplier Acceptance *	true	Legal Declaration *
		Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
TN3015H-6T	7AVP*306HMM1	A	3068	2019-04-12
Amount	UoM	Unit type	ST ECOPACK Grade	
1900.00	mg	Each	ECOPACK2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
NA	NA	NA		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy		
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape
SIP	10.2-15.5-4.5	3	Through-hole
Comment	TO 220 NI CLIP		

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)
7c-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)
10a	Electrical and electronic components which contain lead in a glass or ceramic, in a glass or ceramic matrix compound, in a glass-ceramic material, or in a glass-ceramic matrix compound. This exemption does not cover the use of lead in: — glass in bulbs and glaze of spark plugs, — dielectric ceramic materials of components listed under 10(b), 10(c) and 10(d)

QueryList : California Prop65 list, dated 23rd November 2018			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.34	Die	180
Lead	29.93	Die - Soft solder	15751
Lead-Borate Glass	1.59	Die	836

QueryList : REACH-15th January 2019				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	31.52	Die - Soft solder	16587
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	24.66	Die	762845
Lead	1000 ppm	6.85	Soft solder	920360

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	7AVP*306HMM1					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	32.329	mg	supplier	die	Silicon (Si)	7440-21-3		7.247	mg	224164	3814
				supplier	metallization	Gold (Au)	7440-57-5		0.028	mg	866	15
				supplier	metallization	Nickel (Ni)	7440-02-0		0.145	mg	4485	76
				SVHC	Passivation	Lead (Pb)	7439-92-1	7c-I-Electrical and e	23.074	mg	713725	12144
				supplier	Passivation	Silicon Oxide	7631-86-9		0.041	mg	1268	22
				supplier	back side metallization	Gold (Au)	7440-57-5		0.009	mg	278	5
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.197	mg	6094	104
Leadframe	M-004 Copper and its alloys	1253.003	mg	JIG-R & California 65	glass coating	Lead-Borate Glass	65997-18-4	7c-I-Electrical and e	1.588	mg	49120	836
				supplier	alloy	Copper (Cu)	7440-50-8		1251.374	mg	998700	658618
				supplier	alloy	Iron (Fe)	7439-89-6		1.253	mg	1000	659
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.376	mg	300	198
Soft solder	Solder	7.446	mg	SVHC	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	6.853	mg	920360	3607
				supplier	solder	Silver (Ag)	7440-22-4		0.185	mg	24846	97
				supplier	solder	Tin (Sn)	7440-31-5		0.371	mg	49825	195
				supplier	solder	flux residue	Proprietary		0.037	mg	4969	19
Encapsulation	M-011 Other inorganic materials	569.235	mg	supplier	mold compound	Silica, vitreous	60676-86-0		432.618	mg	759999	227694
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		58.062	mg	102000	30559
				supplier	mold compound	Phenol resin	9003-35-4		34.154	mg	60000	17976
				supplier	mold compound	Others	Proprietary		28.462	mg	50000	14980
				supplier	mold compound	Metal hydroxide	21645-51-2		11.385	mg	20001	5992
				supplier	mold compound	Carbon black	1333-86-4		4.554	mg	8000	2397
Connections coating	Solder	6.362	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.362	mg	1000000	3348
Clip		31.625	mg	supplier	alloy	Copper (Cu)	7440-50-8		31.625	mg	1000000	16645